



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

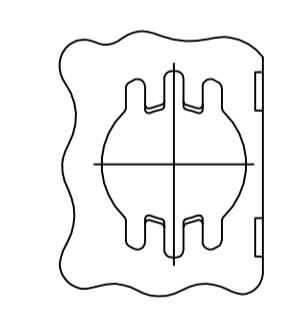
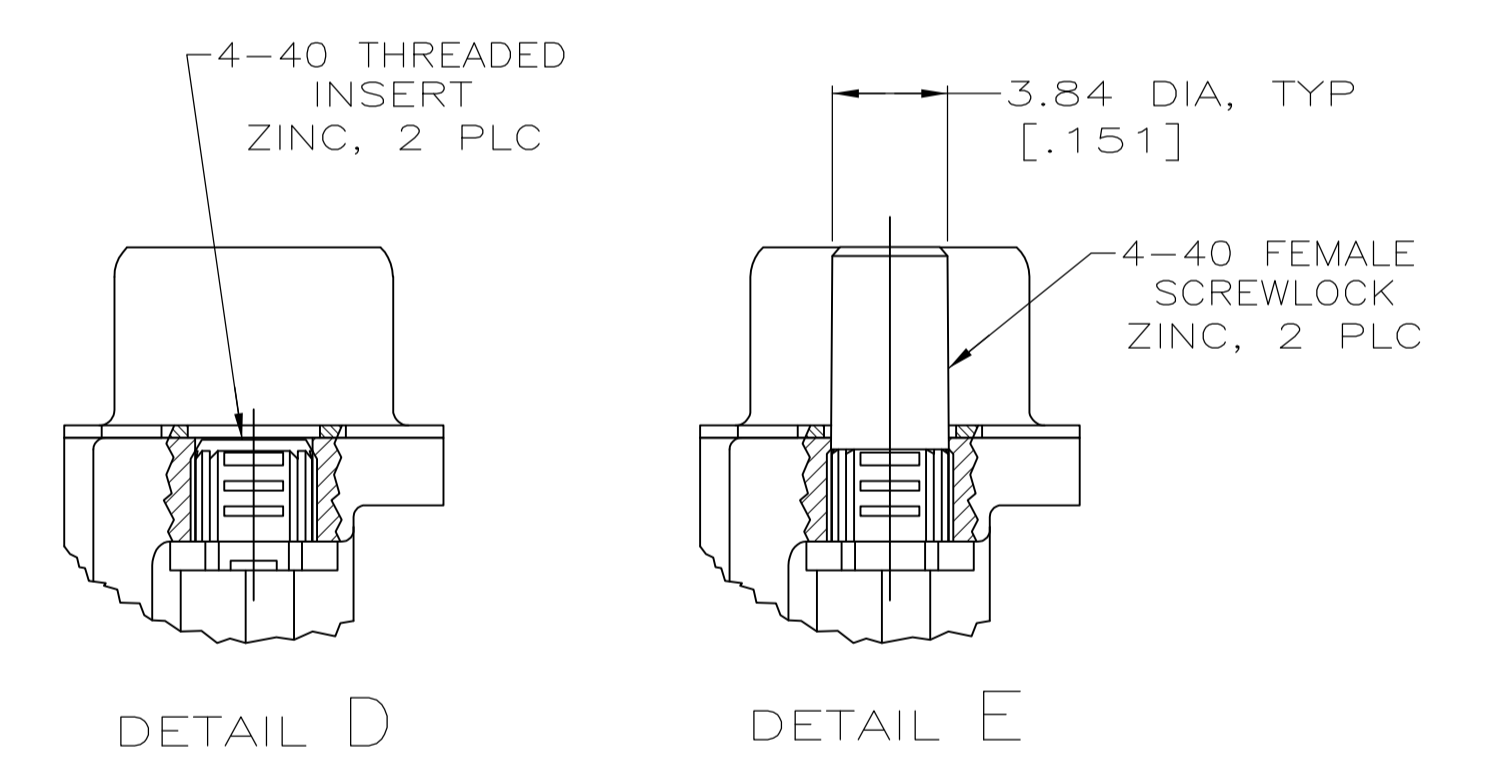
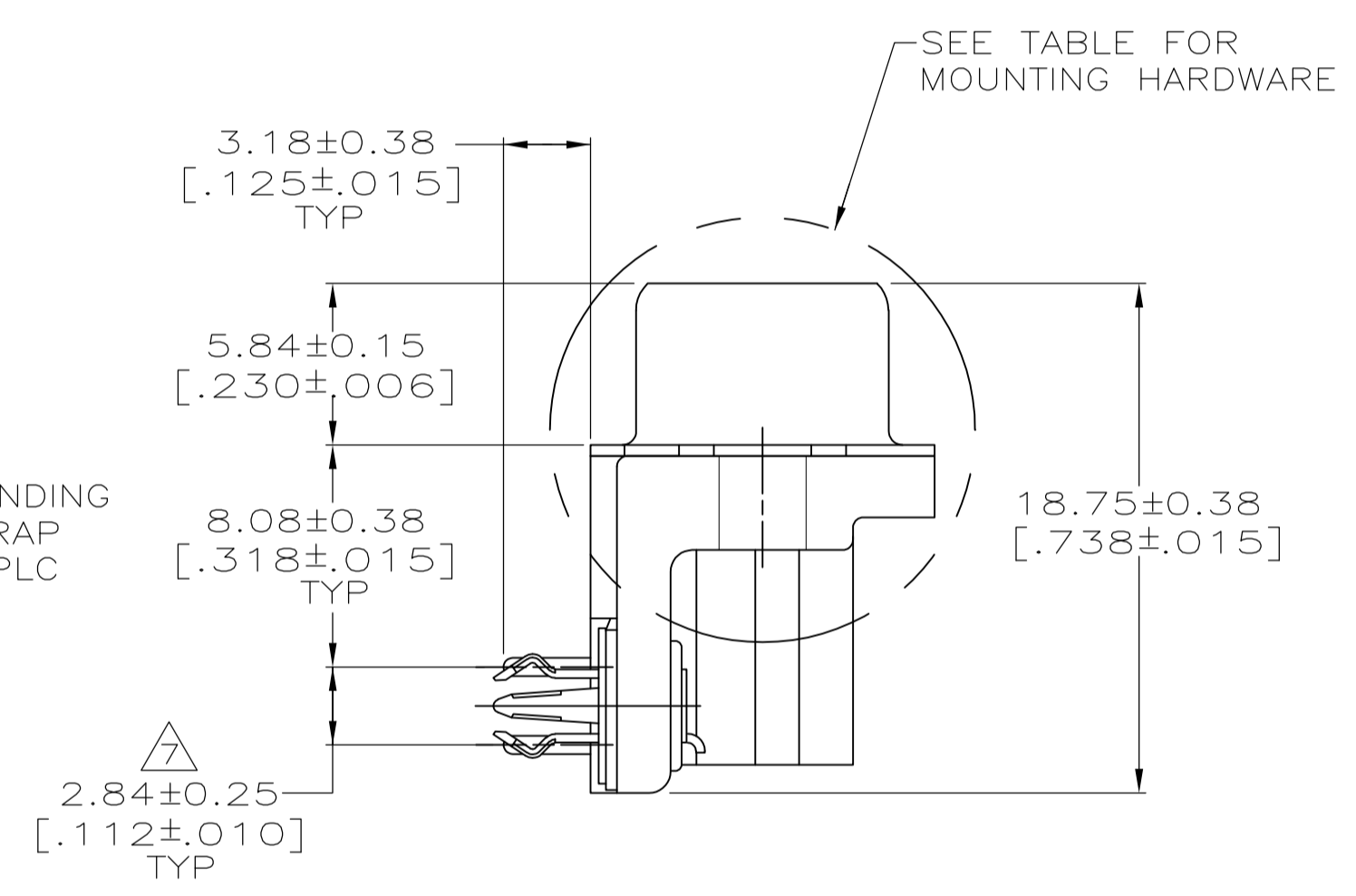
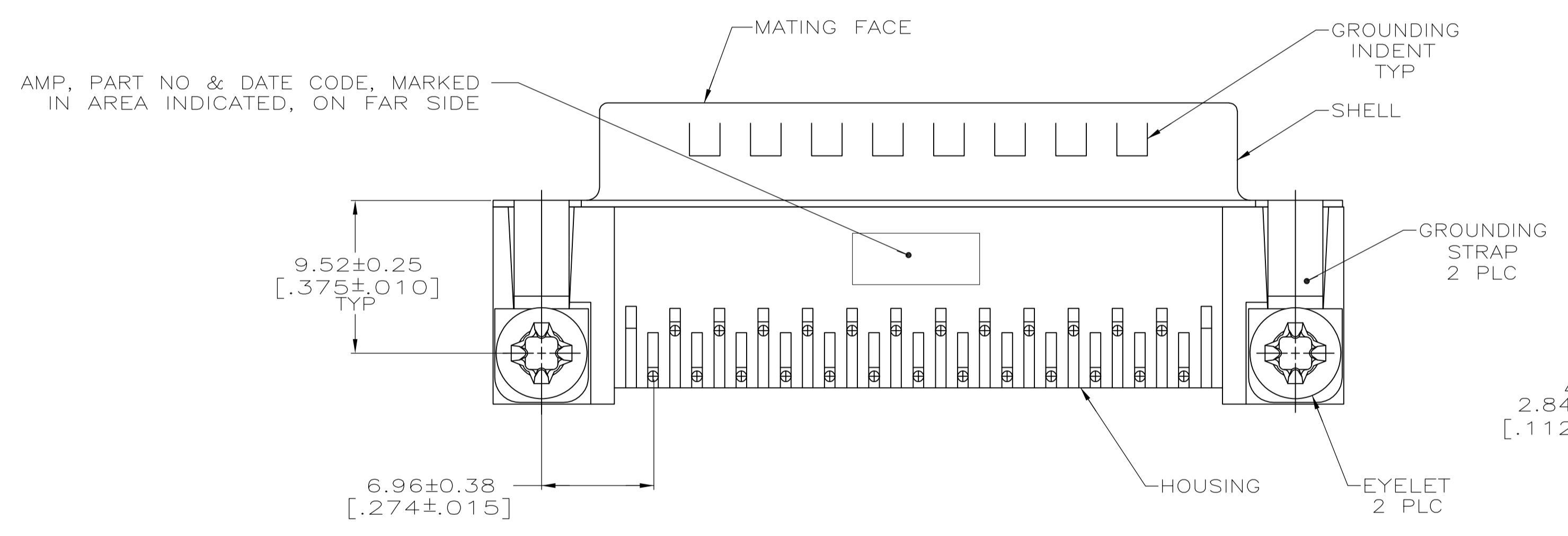
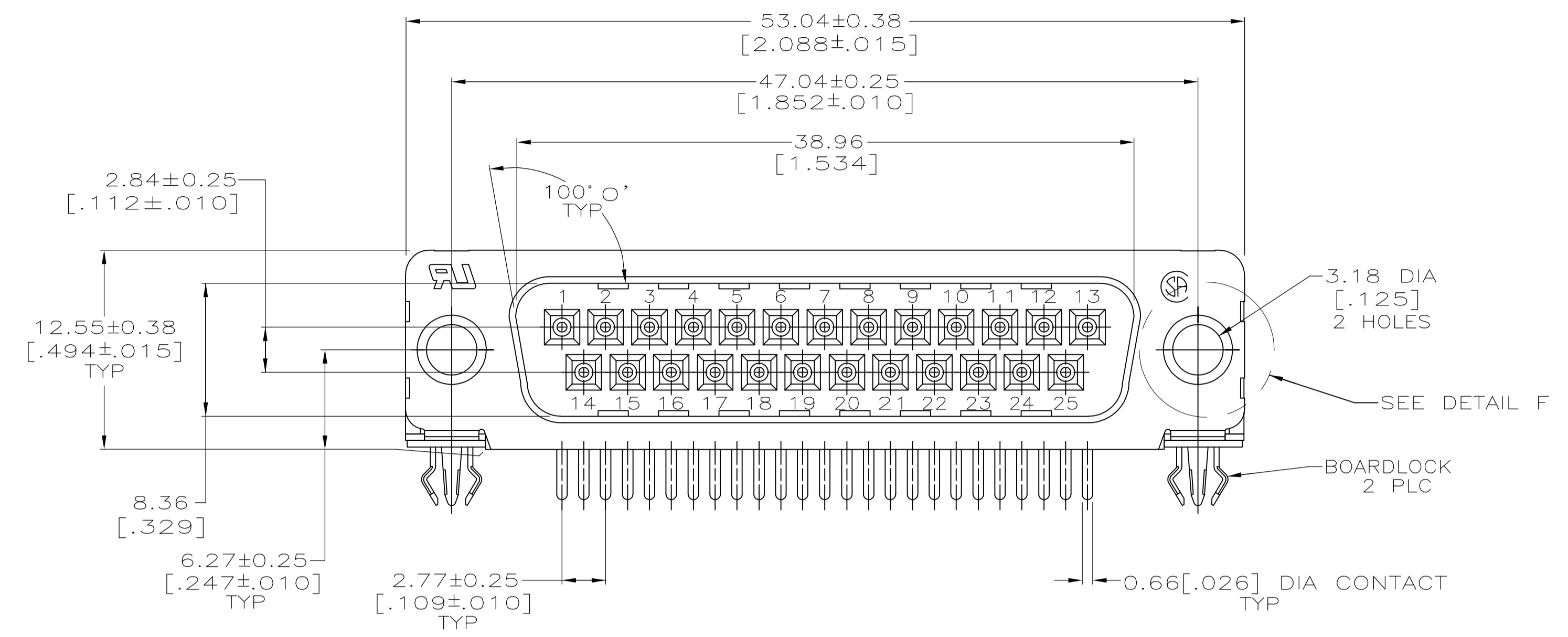
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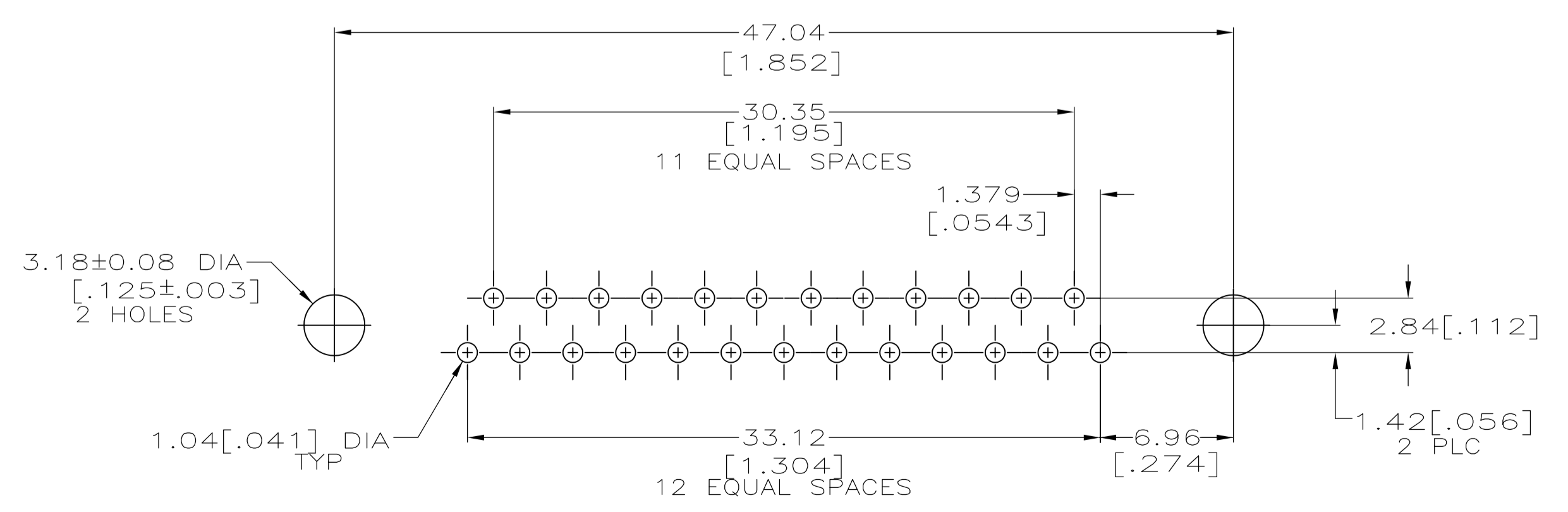
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



- ① HOUSING: NYLON OR POLYESTER, FLAME RETARDANT 94V-0 RATED, GLASS FILLED, BLACK.
SHELLS: CARBON STEEL.
CONTACTS: BRASS.
BOARDLOCKS: COPPER ALLOY.
EYELETS: BRASS.
- ② SHELLS: 2.54μm[.000100] MIN TIN OVER 1.27μm[.000050] MIN COPPER.
EYELETS: 5.08μm[.000200] MIN TIN OVER COPPER FLASH.
CONTACTS: SEE TABLE.
BOARDLOCKS: SEE TABLE.
INSERTS: CLEAR CHROMATE.
SCREWLOCKS: CLEAR CHROMATE.
- ③ GOLD FLASH ON THE MATING SURFACES, 2.54μm[.000100] MIN TIN OR TIN-LEAD PLATE ON THE SOLDER END, 1.27μm[.000050] MIN NICKEL UNDERPLATE ON THE ENTIRE CONTACT.
- ④ 0.76μm[.000030] MIN GOLD PLATE ON THE MATING SURFACES, 2.54μm[.000100] MIN TIN OR TIN-LEAD PLATE ON THE SOLDER END, 1.27μm[.000050] MIN NICKEL UNDERPLATE ON THE ENTIRE CONTACT
-OR-
GOLD FLASH OVER PALLADIUM-NICKEL PLATE, 0.76μm[.000030] MIN TOTAL ON THE MATING SURFACES, 2.54μm[.000100] MIN TIN OR TIN-LEAD PLATE ON THE SOLDER END, 1.27μm[.000050] MIN NICKEL UNDERPLATE ON THE ENTIRE CONTACT.
- ⑤ 5.08μm[.000200] MIN TIN-LEAD OVER 1.27μm [.000050] MIN NICKEL.
- ⑥ 5.08μm[.000200] MIN TIN OVER 1.27μm [.000050] MIN NICKEL.
- ⑦ DIMENSION APPLIES FROM CENTER OF CONTACTS.
- ⑧ SUPERSEDED BY 747842-2.
- ⑨ OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI.



FOR -5 AND -6 ONLY
DETAIL F
2 PLC



RECOMMENDED P.C. BOARD MOUNTING DIMENSIONS
P.C. BOARD THICKNESS: 1.57[.062]

SEE DETAIL E	⑥	④	OBSOLETE	6-747842-9
SEE DETAIL D	⑥	④	ACTIVE	6-747842-8
SEE DETAIL E	⑤	③	ACTIVE	6-747842-7
SEE DETAIL D	⑤	④	ACTIVE	747842-6
-	⑤	③	-	747842-5
-	⑤	④	ACTIVE	747842-4
-	⑤	③	-	747842-3
-	⑤	④	-	747842-2
-	⑤	③	⑧	747842-1
MOUNTING HARDWARE	BOARDLOCK FINISH	CONTACT FINISH	PART STATUS	PART NO

THIS DRAWING IS A CONTROLLED DOCUMENT. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009.

DIMENSIONS: mm [INCHES]	TOLERANCES UNLESS OTHERWISE SPECIFIED:	DWG: W.G. LENKER	10-5-89
0 PLC ± -	1 PLC ± -	CHK: R. STONE	2-5-90
2 PLC ± 0.13[.005]	3 PLC ± -	APVD: -	-
4 PLC ± -	ANGLES ± 2°	NAME: -	-

STE TE Connectivity

PLUG ASSEMBLY, SIZE 3, 25 POSITION, RIGHT ANGLE, FRONT METAL SHELL, .318 SERIES, BOARDLOCKS, AMPLIMITE HD-20

108-40025

114-40010

00779C=747842

CUSTOMER DRAWING SCALE 4:1 SHEET 1 OF 1 REV U